Abstracts

Interconnects and transitions in multilayer LTCC multichip modules for 24 GHz ISM-band applications

W. Simon, R. Kulke, A. Wien, M. Rittweger, I. Wolff, A. Girard and J.-P. Bertinet. "Interconnects and transitions in multilayer LTCC multichip modules for 24 GHz ISM-band applications." 2000 MTT-S International Microwave Symposium Digest 00.2 (2000 Vol. II [MWSYM]): 1047-1050.

Multilayer LTCC substrates with screen printed conductors are considered as a key technology for coming RF wireless communication and automotive applications. Small but expensive MMICs should be integrated in a much cheaper LTCC environment to become a multichip module (MCM). Interconnects between the environmental waveguides and the integrated chips have been designed, optimized, fabricated and evaluated by the authors, which are partners in the European R&D project RAMP.

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